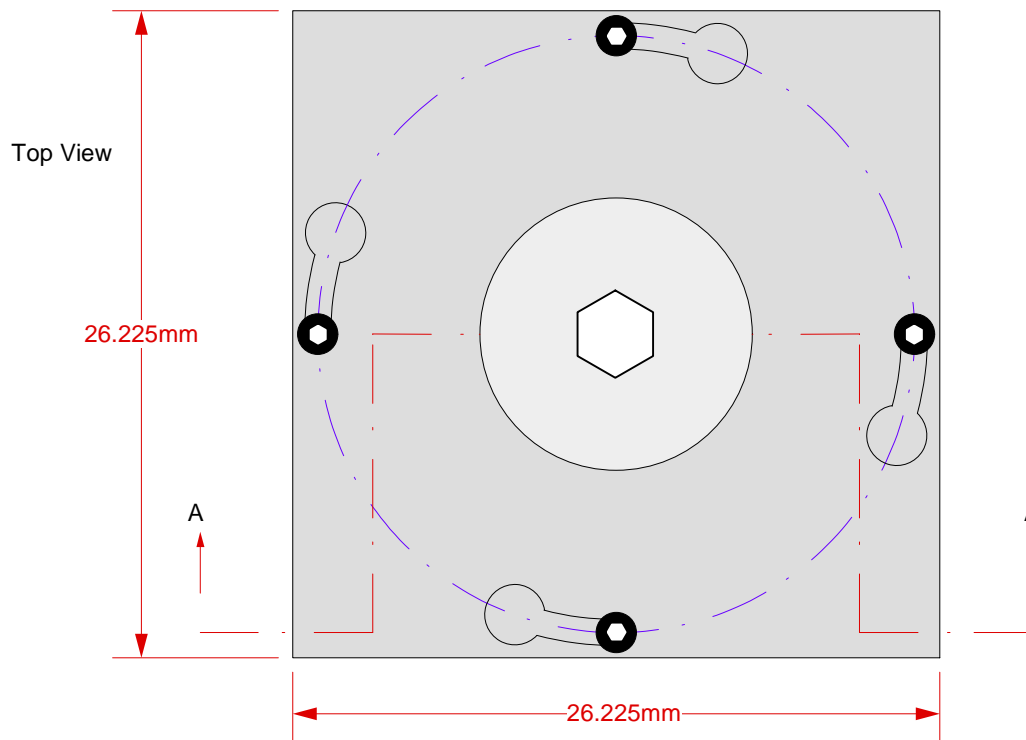


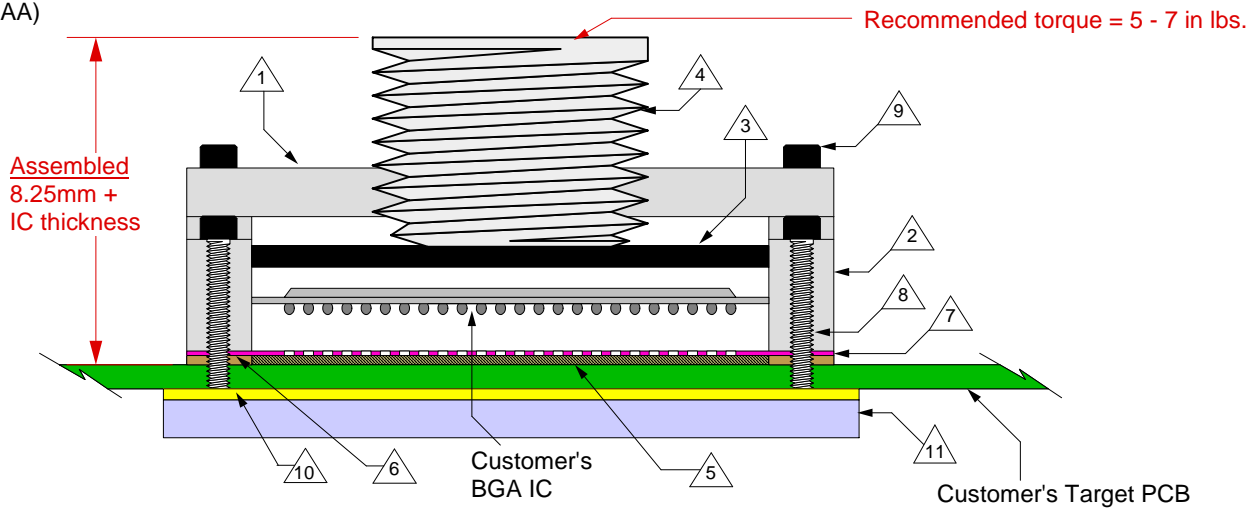
# GHz BGA Socket - Direct mount, solderless

## Features


- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



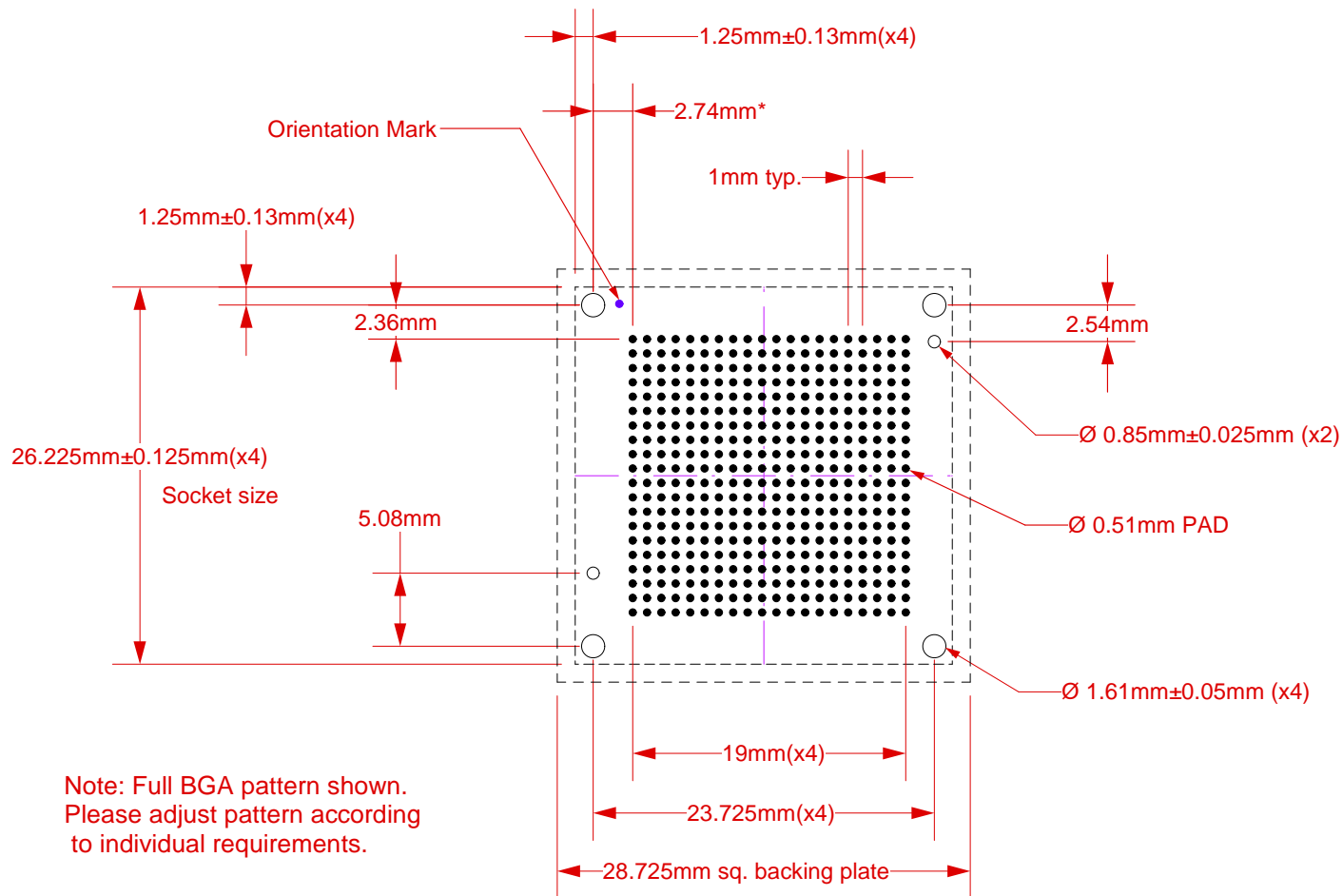
Side View  
(Section AA)



- |    |  |
|----|--|
| 1  | Socket Lid: Black anodized Aluminum.<br>Thickness = 2.5mm.   |
| 2  | Socket base: Black anodized Aluminum.<br>Thickness = 5mm.  |
| 3  | Compression Plate: Black anodized Aluminum.<br>Thickness = 2.5mm.  |
| 4  | Compression screw: Black anodized Aluminum.<br>Thickness = 5mm, Hex socket = 5mm.  |
| 5  | Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).<br>Thickness = 0.75mm. |
| 6  | Elastomer Guide: Non-clad FR4.<br>Thickness = 0.725mm.   |
| 7  | Ball Guide: Kapton polyimide.  |
| 8  | Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long.                                      |
| 9  | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.   |
| 10 | Insulation Plate: FR4/G10, 1.59mm thick.   |
| 11 | Backing Plate: Anodized Aluminum 6.35mm thick.   |

	<b>SG-BGA-6202 Drawing</b>	Status: Released	Scale: -	Rev: C
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 10/27/06
		File: SG-BGA-6202 Dwg.mcd	Modified: 7/8/09, AE	

All tolerances:  $\pm 0.125\text{mm}$  (unless stated otherwise). Materials and specifications are subject to change without notice.



Target PCB Recommendations


Total thickness: 1.6mm min.

Plating: Gold or Solder finish

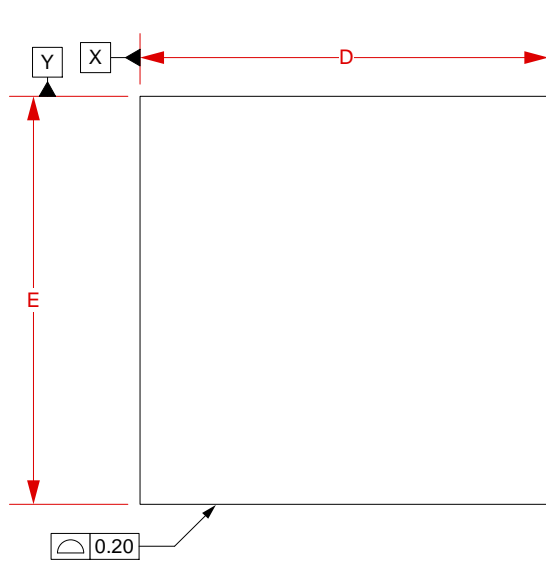
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

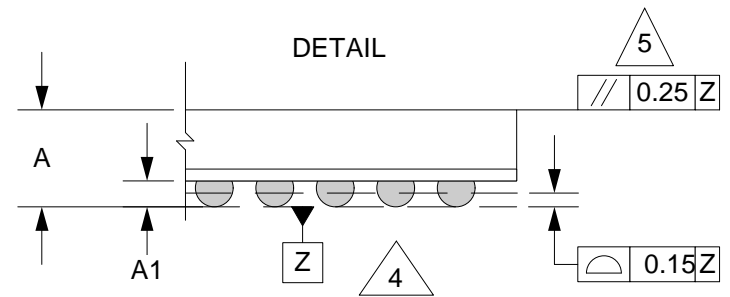
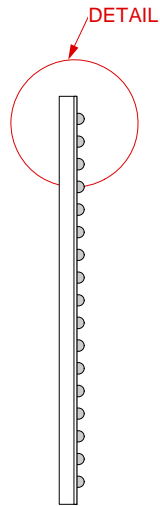
Recommended PCB Layout Tolerances:  $\pm 0.025\text{mm}$  [ $\pm 0.001''$ ] unless stated otherwise.

 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p><b>SG-BGA-6202 Drawing</b></p>	<p>Status: Released</p>	<p>Scale: 2:1</p>	<p>Rev: C</p>
	<p>Drawing: J. Glab</p>	<p>Date: 10/27/06</p>	<p>File: SG-BGA-6202 Dwg.mcd</p>	<p>Modified: 7/8/09, AE</p>

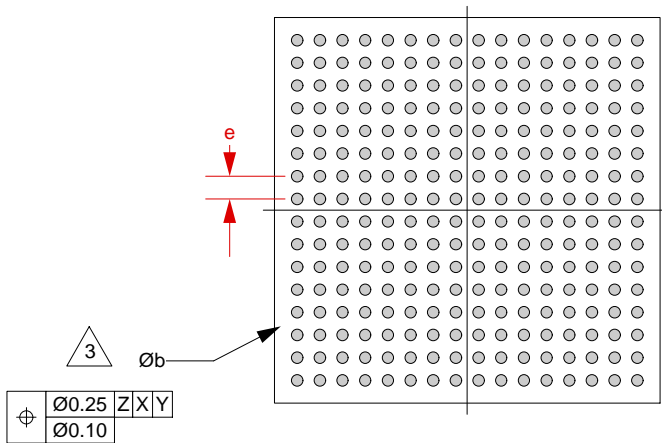
TOP VIEW  
(Reference Only)



SIDE VIEW  
(Reference Only)




BOTTOM VIEW  
(Reference Only)



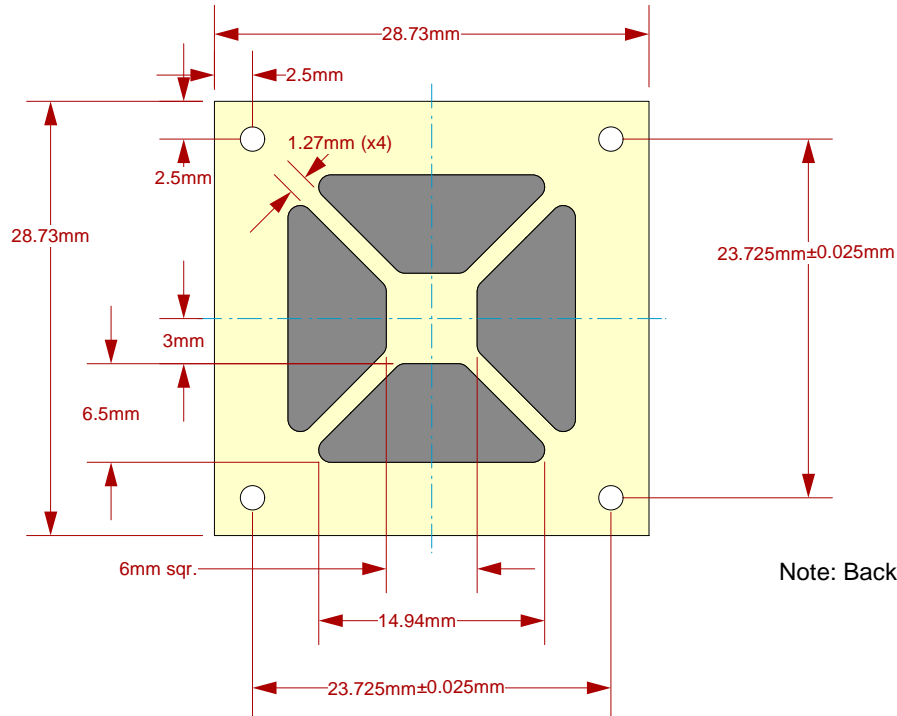
- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.2
A1	0.3	0.5
b		0.7
D	21.00 BSC	
E	21.00 BSC	
e	1.0 BSC	

Array 20x20

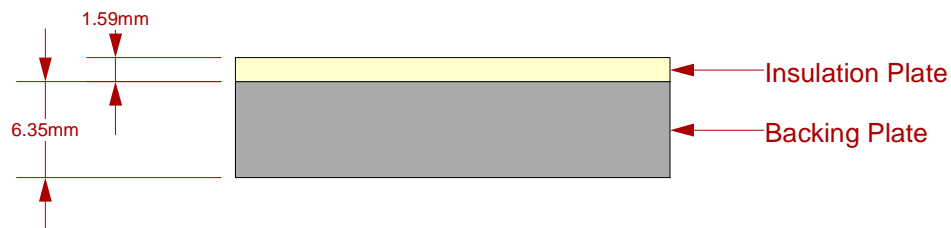
 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<b>SG-BGA-6202 Drawing</b>	Status: Released	Scale: -	Rev: C
	Drawing: J. Glab		Date: 10/27/06	
	File: SG-BGA-6202 Dwg.mcd		Modified: 7/8/09, AE	

Top View




Note: Backing plate holes are tapped to accept 0-80 screws.

Side View



Description: Backing Plate with Insulation Plate

	<b>SG-BGA-6202 Drawing</b>	Status: Released	Scale: -	Rev: C
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		File: SG-BGA-6202 Dwg.mcd	Modified: 7/8/09, AE	

All tolerances:  $\pm 0.125\text{mm}$  (unless stated otherwise). Materials and specifications are subject to change without notice.